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| Electronic Patent Application Fee Transmittal | | | | |
| Application Number: | | 10049270 | | |
| Filing Date: | | 27-Jun-2002 | | |
| Title of Invention: | | MULTILAYER PRINTED WIRING BOARD, SOLDER RESIST COMPOSITION, METHOD FOR MANUFACTURING MULTILAYER PRINTED WIRING BOARD, AND SEMICONDUCTOR DEVICE | | |
| First Named Inventor/Applicant Name: | | Hui Zhong | | |
| Filer: | | Marvin Jay Spivak/Liping Tan | | |
| Attorney Docket Number: | | 312302US40PCT | | |
| Filed as Large Entity | | | | |
| U.S. National Stage under 35 USC 371 Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
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| Extension - 2 months with \$0 paid | 1252 | 1 | 490 | 490 |

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